

MB88310 and MB88311

CMOS Input/Output Expanders

The Fujitsu MB88310 and MB88311 are peripheral integrated circuits that can be connected to a 4-bit or 8-bit single-chip microcomputer (MCU) to provide additional I/O ports. Besides furnishing simple I/O port expansion, the MB88310 and MB88311 can AND or OR port data with data and instruction from the MCU.

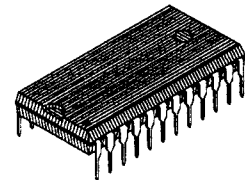
The MB88310 and MB88311 are pseudo-bidirectional ports. They are accessed in 4-bit units, but each individual bit can be used for either input or output, and input and output can be intermixed. The interface to the MCU requires only the connection of a 4-bit interface port and a strobe signal. All output ports of the MB88310 are open-drain, MB88311 output ports all have quasi pull-up resistors. The output ports for both chips are reset to the high-impedance state at power-up.

Both ICs are fabricated with a silicon-gate CMOS process and packaged in a 24-pin plastic DIP or flat package (SOP). They are powered with a single +5V power supply and operate over an ambient temperature range of -40°C to $+85^{\circ}\text{C}$.

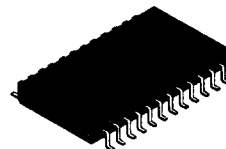
The MB87077 is packaged in a 24-pin plastic DIP or small outline package SOP.

- CMOS Version of Fujitsu MB88304/88305
- Four 4-bit I/O ports (16 lines)
- Four Functions: parallel input, parallel output, AND output, and OR output
- AND and OR functions provide individual output capability
- Single-bit input/output: Input and output can be intermixed on each port
- High output drive
- Built-in power-on reset circuit
- $\overline{\text{CS}}$ pin for simplified input/output expansion
- Two output circuit types:
 - Open-drain output (MB88310)
 - Quasi pulled up output (MB88311)
- Easily connectable to MCUs with 8243 interface
- Single +5V power supply
- -40°C to $+85^{\circ}\text{C}$ operating temperature range
- Silicon-gate CMOS process
- Package and Ordering Information:
 - 24-pin plastic packages,
 - DIP, order as MB88310P and MB88311P or
 - SOP, order as MB88310PF and MB88311PF

Note: Permanent device damage may occur if absolute maximum ratings are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

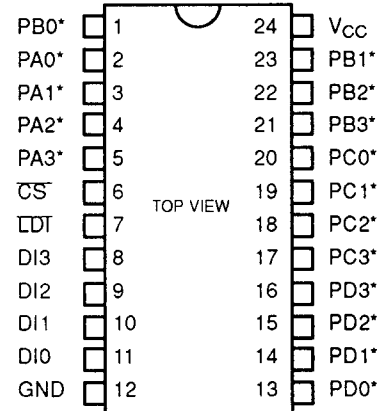


Plastic DIP
(DIP-24P-M02)



Plastic SOP
(FPT-24P-M02)

PIN ASSIGNMENT



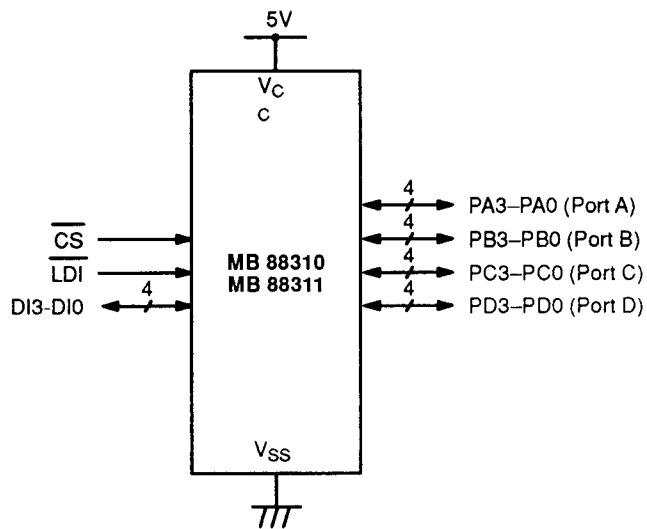
* { MB88310: Open-drain outputs
MB88311: Quasi pulled up outputs

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

Logic Symbol

Processor
Interface

Expansion
Ports



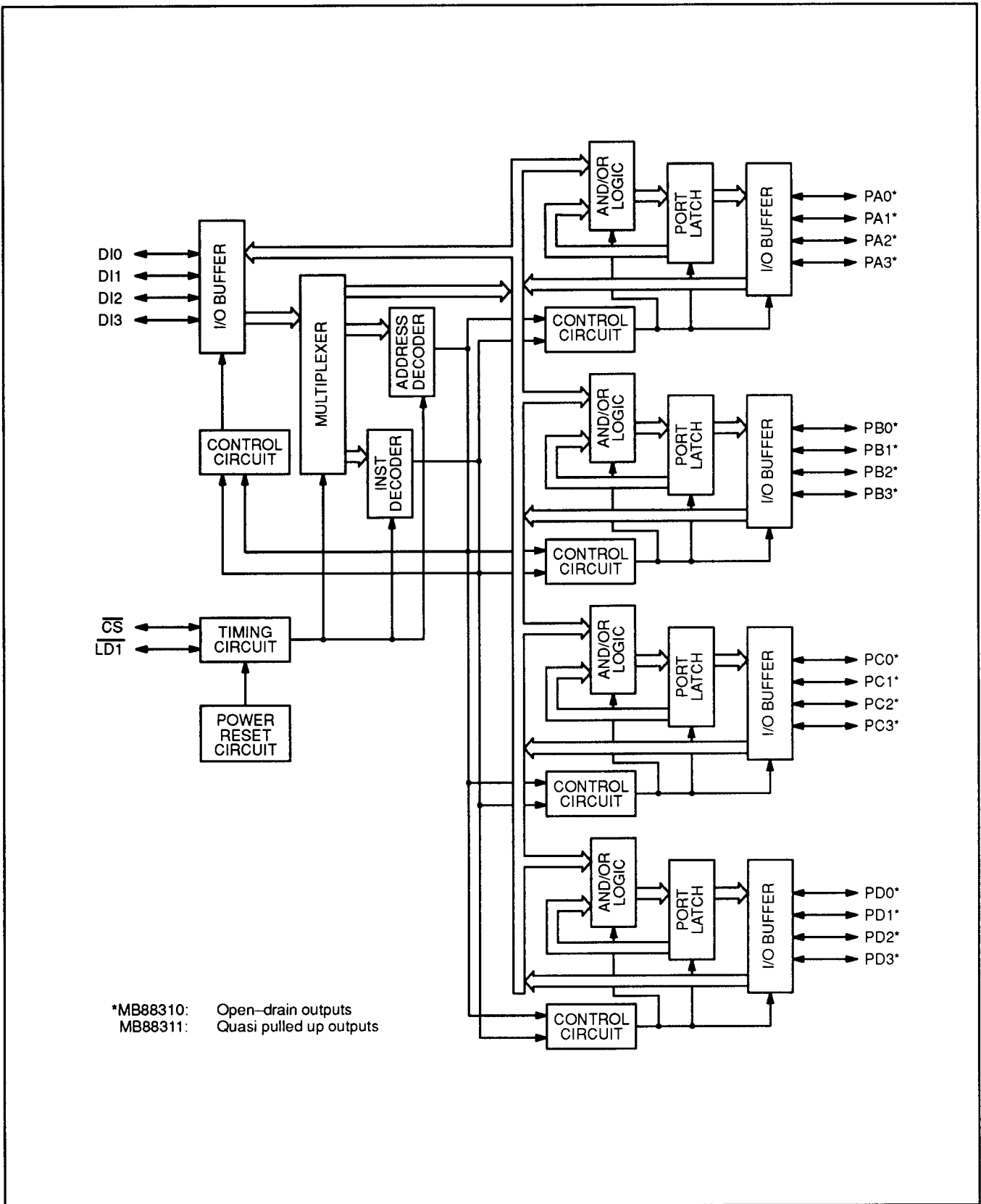


Figure 1. Block Diagram

Pin Description

Both MB88310 and MB88311 have two interfaces. One is the processor interface; \overline{CS} , \overline{LDI} and DI3 – DI0, which are used for the processor to communicate with the MB 88310/88311 devices. The second interface is the expansion I/O ports, Ports A, B, C and D, which serve as an expansion of the processor's I/O.

Table 1. Pin Description

Symbol	Pin No.	Type	Name and Function
V_{CC}	24	–	V_{CC} : is the +5V power supply pin.
GND	12	–	GND : is the ground pin.
\overline{CS}	6	I	Chip Select : is a low-level-sence high-impedance input. A low level on this input selects the device. This input is TTL-compatible.
LDI	7	I	Load Data Input : is an edge-triggered strobe input. The operation code and address code on DI0 to DI3 are latched at the \overline{LDI} falling edge. The data transferred via DI0 to DI3 becomes valid on the rising edge of the \overline{LDI} input.
DI3 to DI0	8 to 11	I/O	Data Bus : is a 4-bit bidirectional port used for interface to the MCU. The operation code and address code provided by the MCU on this port are latched at the falling edge of the \overline{LDI} strobe input, and input/output data is transferred at the rising edge of the \overline{LDI} . The DI port remains in the high-impedance state except when the input operation is executed.
PA0 to PA3	2 to 5	I/O	<p>Ports A, B, C and D are 4-bit bidirectional ports used as expansion I/O ports. These four ports are addressed by address codes provided by the MCU.</p> <p>When an input operation code is given by the MCU, data on the addressed port is transferred to the DI0 to DI3 at the rising edge of the \overline{LDI}. When an output operation code is provided, data on the DI0 to DI3 is transferred and latched to the addressed port at the rising edge of the \overline{LDI}. Logical operations are also possible, in which data on the addressed port is ANDed or ORed with data on the DI0 to DI3 and the result is latched at the addressed port at the rising edge of the \overline{LDI}.</p> <p>After a power-on reset, Ports A to D are all set to the high-impedance state. An individual port is released from the high-impedance state when the OUT, AND, or OR function is applied to it. (Since the MB 88310 has open-drain outputs, a line returns to the high-impedance state when an "1" is written on it.)</p>
PB0, PB1 to PB3	1, 21 to 23	I/O	
PC0 to PC3	20 to 17	I/O	
PD0 to PD3	16 to 13	I/O	

Functional Description

The four 4-bit I/O ports of MB88310 and MB88311 are labelled port A, port B, port C and port D (PA, PB, PC, and PD). They serve as expansion I/O ports for a one-chip microcomputer (MCU) and can be accessed via an MCU port. Their functions are as follows:

- Data transfer from the MCU to port A, B, C, or D
- Data transfer from port A, B, C, or D to the MCU
- ANDing of the port A, B, C, or D data with MCU data and latching of the result at port A, B, C, or D
- ORing of the port A, B, C, or D data with MCU data and latching of the result at port A, B, C, or D

For interface to the MCU, the ICs have a 4-bit interface port (DI0 to DI3), a strobe input ($\overline{\text{LDI}}$ pin), and a chip select input ($\overline{\text{CS}}$ pin). The interface data consists of two 4-bit units. The first 4 bits give the operation code (2-bits) and address code (2-bits). The second 4-bits are the input or output data. Both 4-bit units are transferred through the interface port (DI0 to DI3) on timings determined by the strobe ($\overline{\text{LDI}}$) signal. MB88310 or MB88311 reads the operation code and address code from the MCU on the falling edge of the $\overline{\text{LDI}}$ signal, and sends or receives the I/O data on the rising edge of $\overline{\text{LDI}}$.

The $\overline{\text{CS}}$ pin is used to read a chip select signal from the MCU's I/O port when two or more MB88310 or MB88311 chips are connected to the MCU.

Ope. Code		Function	Addr. Code		Port Address
DI3	DI2		DI1	DI0	
0	0	IN (Input)	0	0	Port A (PA)
0	1	OUT (Output)	0	1	Port B (PB)
1	0	OR (Logical OR)	1	0	Port C (PC)
1	1	AND (Logical AND)	1	1	Port D (PD)

Power-on Reset

Both ICs contain an internal power-on reset circuit that detects the rise of V_{CC} on the power supply line and holds the chip circuits in the reset state. In the reset state, the interface port (pins DI0 to DI3) is set to the input state, and ports A to D (PA to PD) are in the high-impedance state (except that latched output ports are not reset). The V_{CC} line must rise smoothly for the reset circuit to operate. Regardless of the input level (high or low) of the $\overline{\text{LDI}}$ pin at the moment power is applied, the reset state is released at the first falling edge of the $\overline{\text{LDI}}$ input. A power-on reset also occurs if the supply voltage (V_{CC}) drops to 1 V or less, then recovers to the rated voltage.

Output Mode (Write Mode)

Both ICs have three output modes that correspond to three functions of the MCU: data transfer output (OUT), logical OR (OR), and logical AND (AND).

- OUT** The designated port latches and outputs the 4-bit data transferred from the MCU.
- AND** The 4-bit data transferred from the MCU is ANDed with the 4-bit data of the designated port, which then latches the result as output.
- OR** The 4-bit data transferred from the MCU is ORed with the 4-bit designated port, which then latches the result as output.

The operation code and address code sent from the MCU to pins DI0 to DI3 of either IC are latched on the falling edge of the strobe signal at the $\overline{\text{LDI}}$ pin. The MCU data is read on the rising edge of the strobe signal and sent to the logic circuit of the designated port, where it is processed. The MCU data is then latched as output data.

Input Mode (Read Mode)

The ICs have only one input mode (IN), that corresponds to data input by the MCU.

IN The input data at the port designated by the MCU is read and sent to the MCU via the interface port (DI0 to DI3).

The operation and address code sent from the MCU to pins DI0 to DI3 of either IC are latched on the falling edge of the strobe signal at the $\overline{\text{LDI}}$ pin. If the operation code specifies input, either IC sends data from the port designated by the address code to the MCU via DI0 to DI3.

A power-on reset places the chip in the input mode with ports A to D in the high-impedance state. If only the IN function is used, the ports remain in the high-impedance state thereafter. Release from the high-impedance state takes place when the OUT, AND, or OR function is used.

Both ICs are designed for easy external driving. The MB88310 has open-drain outputs, while the MB88311 outputs have pull-up resistors. For both chips, the input level of a port to be used for input can be read by writing a 1 and performing the IN function. Input and output can therefore be intermixed within the four bits of each of the four ports (A to D).

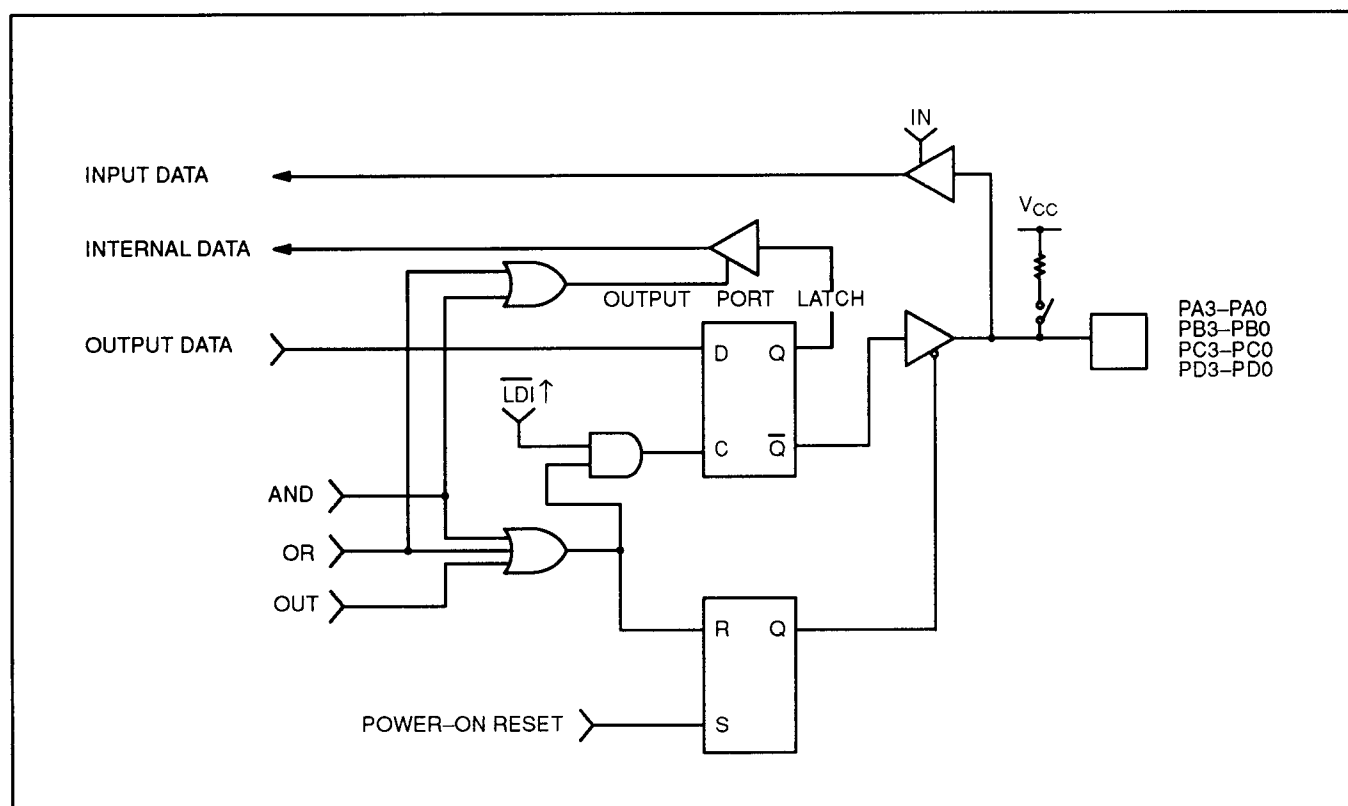


Figure 2. Port Circuit Configuration

Sink Current from Ports A to D

When $V_{OL} \leq 0.45V$, both ICs can sink 5mA (I_{OL}) on each of their 16 I/O lines simultaneously. When this current sinking capability is not required on all of the I/O lines, or when all of the lines do not have to sink 5mA, the driving capability (sink current) of the other I/O lines can be increased according to the characteristics shown in the curve below.

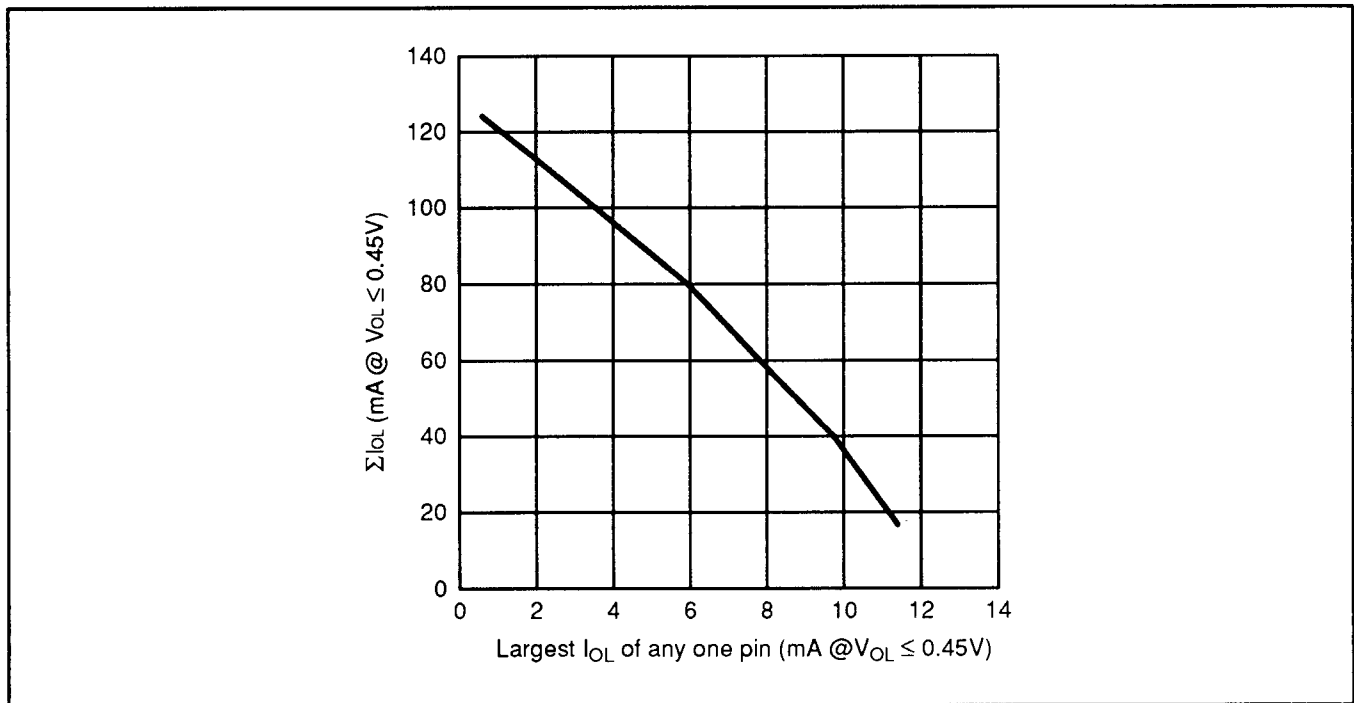


Figure 3. ΣI_{OL} vs I_{OL} (@ $V_{OL} \leq 0.45V$)

For instance, if one of the I/O lines has to sink 9mA, the total I_{OL} (ΣI_{OL}) of all lines can be up to 45mA.

Example-1 : How many I/O lines with 5 TTL loads can be driven?

$$I_{OL} = 5 \times 1.6mA = 8mA$$

$$\Sigma I_{OL} \leq 60mA \text{ (from the total } I_{OL} \text{ characteristics curve)}$$

$$60mA / 8mA = 7 \text{ I/O lines}$$

The chip can drive 7 lines with 5 TTL loads, making a total of 56mA on these lines. The remaining 4mA can be shared among the other 9 I/O lines.

Example-2 : Suppose that two of the load lines have $I_{OL} = 20mA$ (at $V_{OL} \leq 1V$). The MB88310 or MB88311 drive the following loads?

$$2 \text{ I/O lines : } 20mA \text{ (at } V_{OL} \leq 1V)$$

$$8 \text{ I/O lines : } 4mA \text{ (at } V_{OL} \leq 0.45V)$$

$$6 \text{ I/O lines : } 3.2mA \text{ (at } V_{OL} \leq 0.45V)$$

$$\begin{aligned} \text{Total } I_{OL} &= (2 \times 20mA) + (8 \times 4mA) + (6 \times 3.2mA) \\ &= 91.2mA \end{aligned}$$

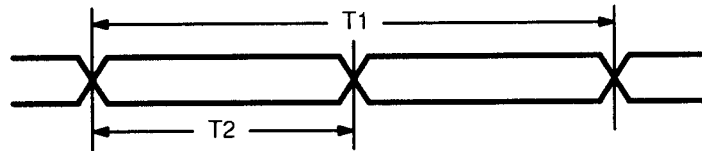
Reading the total I_{OL} characteristics for $I_{OL} = 4mA$, we see that $\Sigma I_{OL} \leq 93mA$. Since $91.2mA \leq 93mA$, the chip can drive these loads.

Note : The allowable total I_{OL} (ΣI_{OL}) depends on the maximum sink current of the lines for which V_{OL} must be equal to or less than 0.4V.

Notice on Using the Input Mode

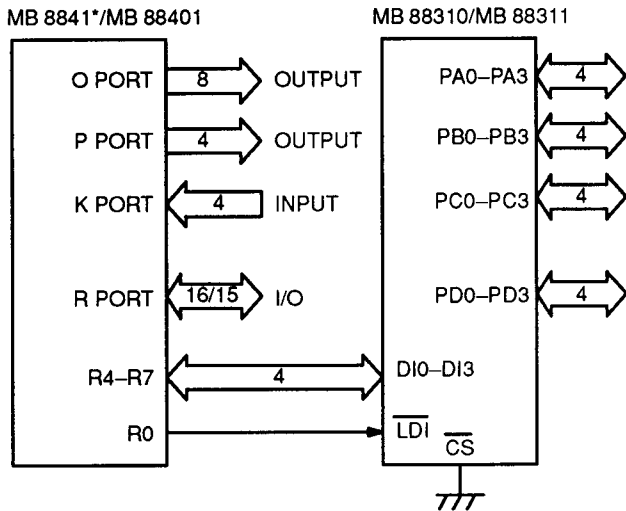
When both devices work in an input mode, with a processor that does not have an 8243 interface, data collision may occur between device's DI3–DI0 port and the processor's data bus. If this occurs, the following limits should be observed.

1. DC collision: Maximum short circuit current for DI3–DI0 = 2.5mA.
2. AC collision: Maximum short circuit current for DI3–DI0 = 30mA at $T2/T1$ (= duty) < 0.1 and $T2 < 1$ ms. (See figure below.)

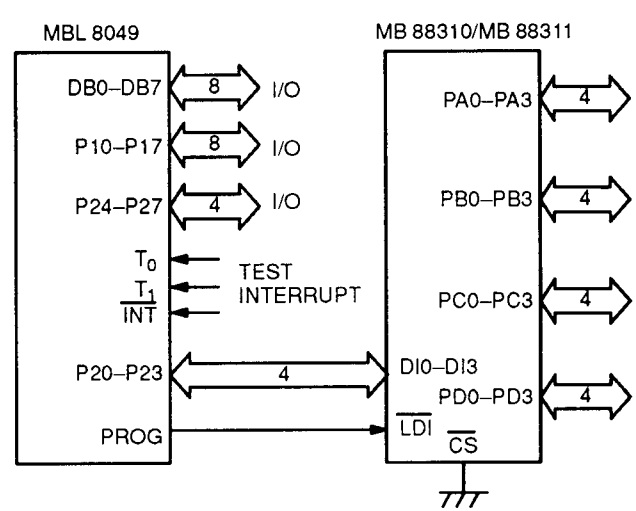


Note: T1 = Period, T2 = Collision Time

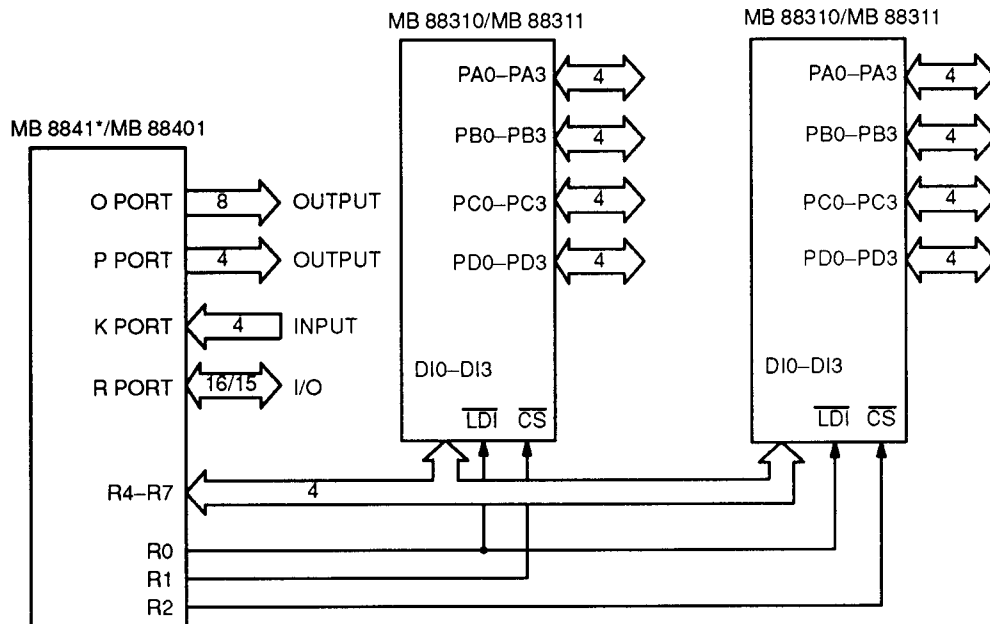
INTERFACE WITH 4-BIT MICROCOMPUTER



INTERFACE WITH 8-BIT MICROCOMPUTER



INTERFACE WITH 4-BIT MICROCOMPUTER



Note : * Output port of MB8841 should be open-drain type.

Figure 4. Typical Applications

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V_{CC}	$V_{SS} - 0.3$ to $+ 7.0$	V
Input Voltage	V_{IN}	$V_{SS} - 0.3$ to $+ 7.0^*$	V
Operating Temperature	T_A	-40 to $+85$	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to $+150$	$^{\circ}C$
Power Dissipation	P_D	1.0	W

NOTE : Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational section of this data sheet. Exposure to ABSOLUTE MAXIMUM RATINGS conditions for extended periods may affect device reliability.

* V_{IN} should not exceed $V_{CC} + 0.3V$.

Recommended Operating Conditions

Parameter	Symbol	Value	Unit
Supply Voltage	V_{CC}	$+5 \pm 10\%$	V
	V_{SS}	0	
Operating Temperature	T_A	-40 to $+85$	$^{\circ}C$

Electrical Characteristics

DC Characteristics

($T_A = -40^{\circ}C$ to $+85^{\circ}C$, $V_{CC} = +5V \pm 10\%$, $V_{SS} = 0V$)

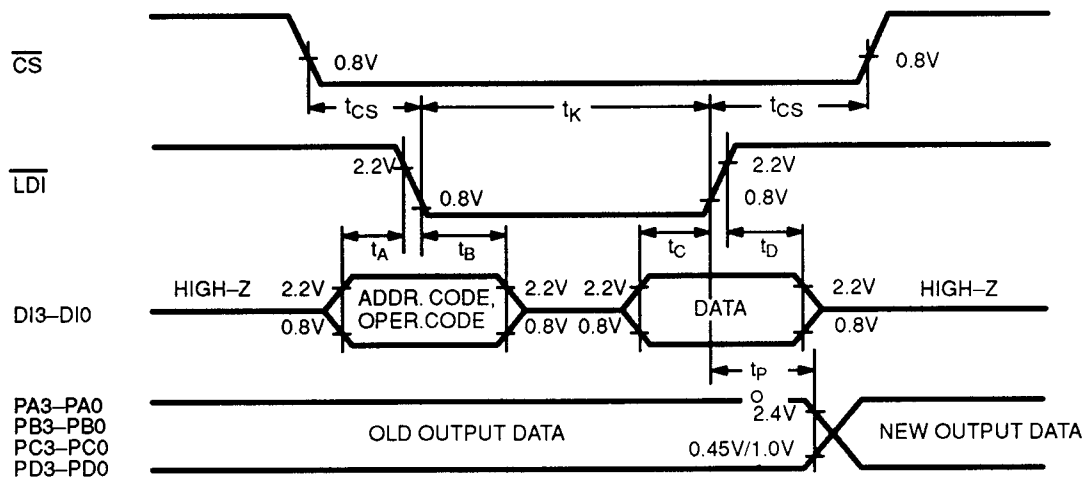
Parameter	Symbol	Values			Unit	Conditions
		Min.	Typ.	Max.		
Input Low Voltage	V_{IL}	$V_{SS} - 0.3$		0.8	V	
Input High Voltage	V_{IH}	2.2		$V_{CC} + 0.3$	V	
Output Low Voltage	Port A to D	V_{OL1}	—	0.45	V	$I_{OL} = 5mA$
		V_{OL2}	—	1.0	V	$I_{OL} = 20mA$
Output Low Voltage	DI0 to DI3	V_{OL3}	—	0.6	V	$I_{OL} = 1.8mA$
Output High Voltage	Ports A to D	V_{OH1}	2.4		V	$I_{OH} = -240\mu A$ (MB 88311)
Output High Voltage	DI0 to DI3	V_{OH2}	2.4		V	$I_{OH} = -100\mu A$
Input Leakage Current	Ports A to D	I_{IL1}	-10	20	μA	$V_{SS} \leq V_{IN} \leq V_{CC}$
	DI0 to DI3, CS, LDI	I_{IL2}	-10	10	μA	$V_{SS} \leq V_{IN} \leq V_{CC}$
Input Current	Ports A to D	I_I		1.0	mA	$V_{IN} = V_{SS}$ (MB 88311)
Total I_{OL} Output Current from 16 Output		ΣI_{OL}		80	mA	Each output current : 5mA
Supply Current	V_{CC}	I_{CC1}		200	μA	All outputs open, Normal operation
		I_{CC2}		1.0	μA	All outputs open, Standby operation, LDI cycle=5 μs

AC Characteristics

($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{CC} = +5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$)

Parameter		Symbol	Values			Unit	Conditions
			Min.	Typ.	Max.		
Address/Op Codes Setup Time	D13 to D10	t_A	100			ns	$C_L = 80\text{pF}$
Address/Op Codes Hold Time	D13 to D10	t_B	60			ns	$C_L = 20\text{pF}$
Data Setup Time	D13 to D10 (Output Mode)	t_C	200			ns	$C_L = 80\text{pF}$
Data Hold Time	D13 to D10 (Output Mode)	t_D	20			ns	$C_L = 20\text{pF}$
Data Output Delay Time	Ports A to D (Output Mode)	t_{PO}			700	ns	$C_L = 100\text{pF}$
$\overline{\text{LDI}}$ Pulse Width	$\overline{\text{LDI}}$	t_K	700			ns	
$\overline{\text{CS}}$ Setup/Hold Time	$\overline{\text{CS}}$	t_{CS}	50			ns	
Input Data Setup/Hold Time	Ports A to D (Output Mode)	t_{LPi}	100			ns	
Data Output Delay Time	D13 to D10 (Input Mode)	t_{ACC}			650	ns	$C_L = 80\text{pF}$
Data Hold Time	D13 to D10 (Input Mode)	t_H	0		150	ns	$C_L = 20\text{pF}$

Output Mode (Write Mode)



Input Mode (Read Mode)

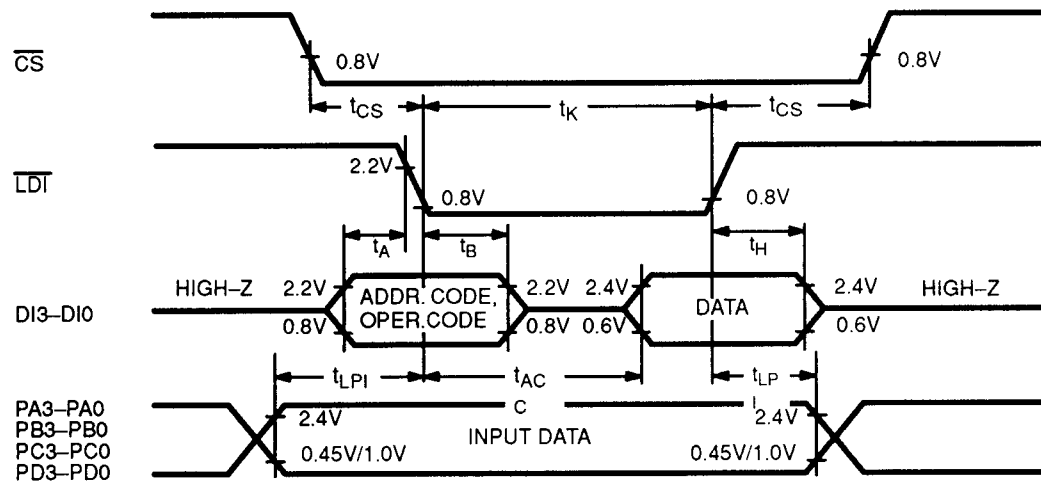
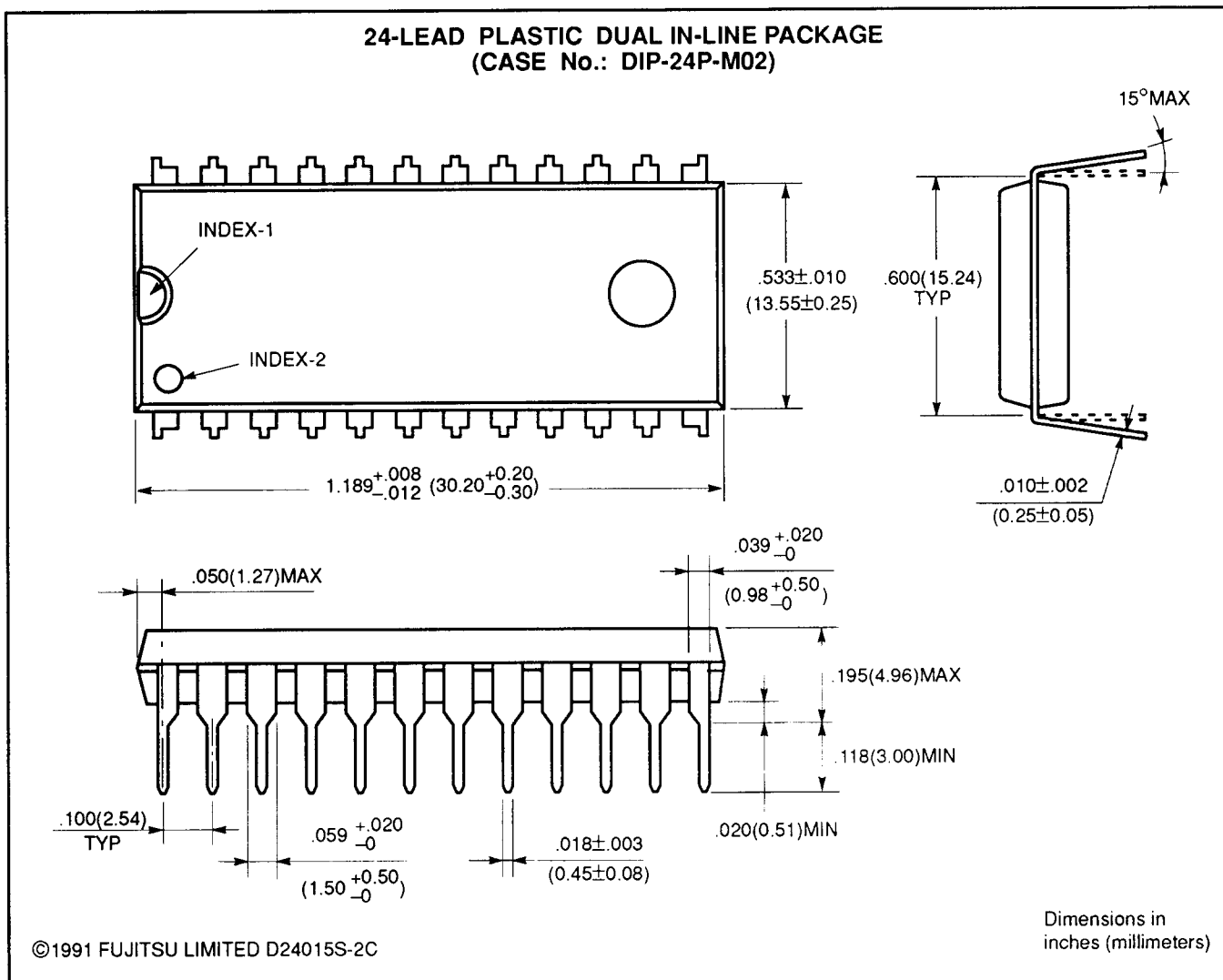


Figure 5. Timing Diagram

Package Dimensions

PLASTIC DIP (Suffix: -P)



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